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Intel® Core™ Ultra Series 3 Processors on COM-HPC Mini

Join TQ-Systems at embedded world 2026 to explore cutting-edge embedded computing powered by the latest Intel® Core™ Ultra Series 3 processor, Intel® Core™ and Intel Atom® processors. Experience the new COM-HPC® Mini standard, delivering up to 41% size reduction[1] and unmatched CPU, GPU, and AI performance—ideal for high-performance edge computing and multi-stream 8K multimedia applications.

See live demos showcasing AI performance and energy efficiency optimization, with real-time comparisons of CPU, GPU, and NPU usage across various workloads. Learn how TQ's scalable x86 Computer-on-Modules and innovative cooling solutions enable fast integration, future-proof designs, and high-speed connectivity with USB4, PCIe Gen4/5, and DisplayPort or HDMI.

Whether you're upgrading existing systems or building next-gen AI-powered solutions, TQ's modular platforms offer the flexibility and performance you need.

Partner Link:
https://www.tq-group.com/en/products/tq-embedded/x86-highlights/

Partner Name

TQ-Systems GmbH

Booth Location

3-249

Solution Names

- COM-HPC Mini module TQMxCU3-HPCM
- Compatible Carrier Board MB-COMHPCM-100100-1

embeddedworld
Exhibition&Conference

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[1] Intel does not control or audit third-party data. You should consult other sources to evaluate accuracy.